

Q-Pad[®] II

January 2015

PRODUCT DESCRIPTION

Foil-Format Grease Replacement for Maximum Heat Transfer

FEATURES AND BENEFITS

- Thermal impedance: 0.22°C-in²/W
 (@50 psi)
- Maximum heat transfer
- Aluminum foil coated both sides
- · Designed to replace thermal grease



Q-Pad[®] II is a composite of aluminum foil coated on both sides with thermally/ electrically conductive Sil-Pad[®] rubber. The material is designed for those applications in which maximum heat transfer is needed and electrical isolation is not required. Q-Pad[®] II is the ideal thermal interface material to replace messy thermal grease compounds.

Q-Pad[®] II eliminates problems associated with grease such as contamination of reflow solder or cleaning operations. Unlike grease, Q-Pad[®] II can be used prior to theseoperations. Q-Pad[®] II also eliminates dust collection which can cause possible surface shorting or heat buildup..

Note: To build a part number, visit our website at www.bergquistcompany.com.

TYPICAL PROPERTIES OF Q-PAD II						
PROPERTY	IMPERIA	_ VALUE	METRIC VALUE		TEST METHOD	
Color	Black		Black		Visual	
Reinforcement Carrier	Aluminum		Aluminum			
Thickness (inch) / (mm)	0.006		0.152		ASTM D374	
Hardness (Shore A)	93		93		ASTM D2240	
Continuous Use Temp (°F) / (°C)	-76 to 356		-60 to 180			
ELECTRICAL						
Dielectric Breakdown Voltage (Vac)	Non-Insulating		Non-Insulating		ASTM D149	
Dielectric Constant (1000 Hz)	NA		NA		ASTM D150	
Volume Resistivity (Ohm-meter)	10 ²		10 ²		ASTM D257	
Flame Rating	V-O		V-O		U.L.94	
THERMAL						
Thermal Conductivity (W/m-K)	2.5		2.5		ASTM D5470	
THERMAL PERFORMANCE vs PRESS	URE					
Press	ure (psi)	10	25	50	100	200
TO-220 Thermal Performance (°C/W)		2.44	1.73	1.23	1.05	0.92
Thermal Impedance (°C-in²/W) (1)		0.52	0.30	0.22	0.15	0.12
I) The ASTM D5470 test fixture was used. The reco	orded value inc	ludes interfac	ial thermal resi	istance. These	values are pro	ovided for

 The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

TYPICAL APPLICATIONS INCLUDE

- Between a transistor and a heat sink
- · Between two large surfaces such as an L-bracket and the chassis of an assembly
- · Between a heat sink and a chassis
- Under electrically isolated power modules or devices such as resistors, transformers and solid state relays

CONFIGURATIONS AVAILABLE

- · Sheet form, die-cut parts and roll form
- · With or without pressure sensitive adhesive

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Disclaimer

Note:

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

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Reference 0.1